

Appl. No. 10/552,540  
Amdt. Dated August 30, 2007  
Reply to Office Action of May 3, 2007

Attorney Docket No. 81844.0044  
Customer No.: 26021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Shigeru TANAKA, et al.  
Serial No: 10/552,540  
Confirmation No.: 2300  
Filed: October 11, 2005  
For: THERMOSETTING RESIN  
COMPOSITION, MULTILAYER  
BODY USING SAME, AND CIRCUIT  
BOARD

Art Unit: 1714  
Examiner: Patrick Dennis  
Niland

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated May 3, 2007, the time for response to which is extended one month by the accompanying petition from August 3, 2007 to September 3, 2007, please amend the above-referenced application as follows:

**Amendments** to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 28 of this paper.